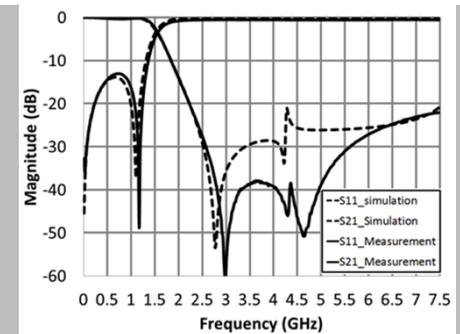
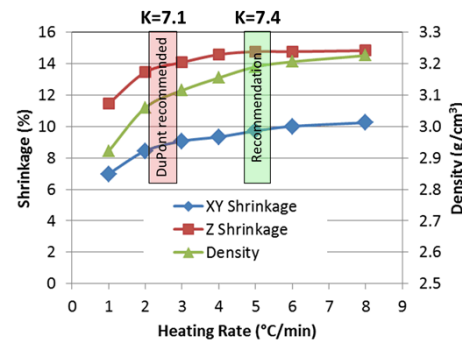
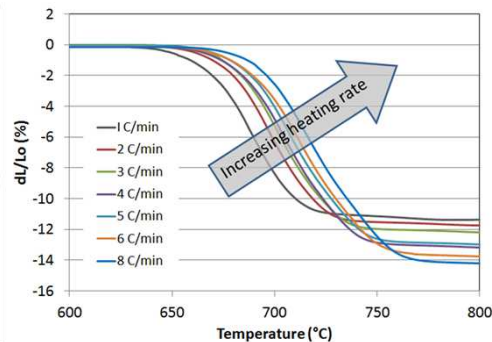


Exceptional service in the national interest



Miniature Lowpass Filters in Low Loss 9k7 Low Temperature Co-fired Ceramics

Steve Dai and Lung-Hwa Hsieh

Sandia National Laboratories, Albuquerque, New Mexico, USA

MMA2016, Seoul, Korea, Jul 3 - 6, 2016



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- Pb-free Low Loss 9k7 LTCC
 - Densification and crystallization
 - Optimized process conditions

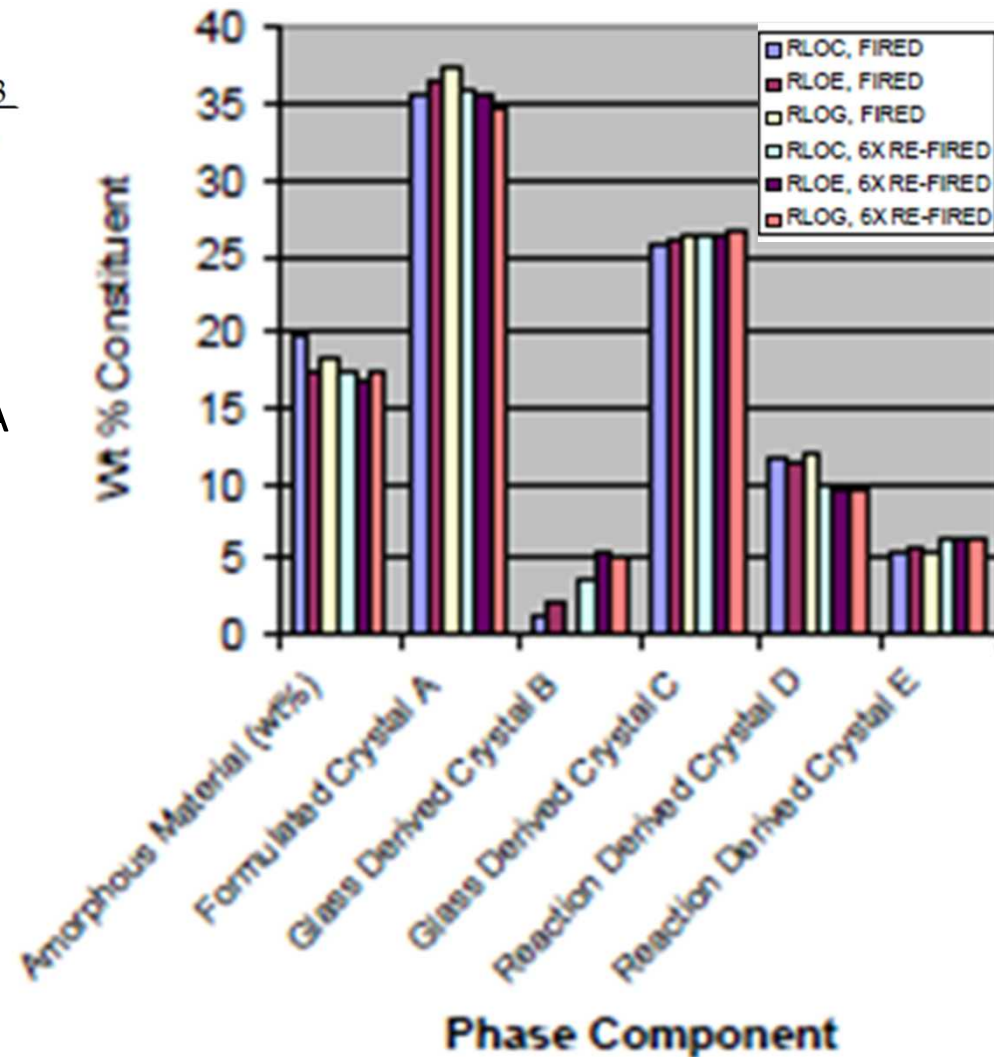
- Low Pass Filters (LPF) in multilayer 9k7 LTCC
 - LPF in 4-layer LTCC
 - Miniaturized LPF in 8-layer LTCC

- Summary

Crystallization in 9k7 LTCC

$$\frac{1}{Q} = \sum \frac{V_i}{Q_i} \approx \frac{V_{glass}}{350} + \frac{V_{cryst.}}{1500} + \frac{V_{Al_2O_3}}{10000}$$

- Low loss achieved via multiple crystallization
 - Ceramic filler = formulated crystal A
 - Glass derived crystals, B and C
 - Reaction derived crystals, D and E
- Role of glass in 9k7
 - Densification via viscous sintering
 - Diffusion controlled multiple crystallization, takes time
- Ramp rate (530-850 °C) critical

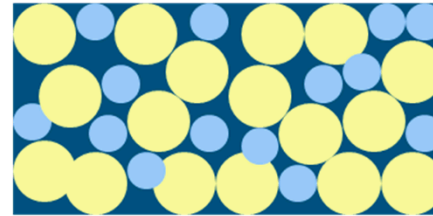


LTCC Base Dielectrics – a composite

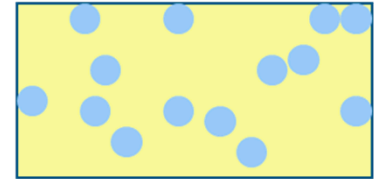
■ Type 1:

- Unreactive, glass as sintering agent for high density
- Example: DuPont 951

Green

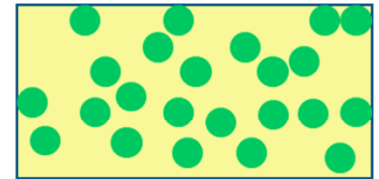
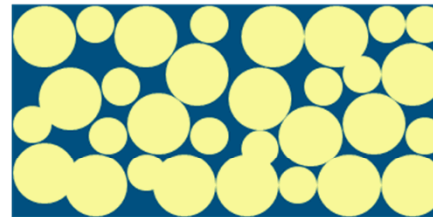


Sintered



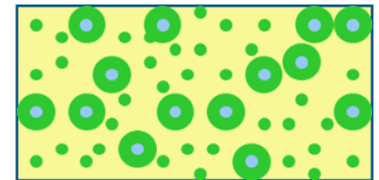
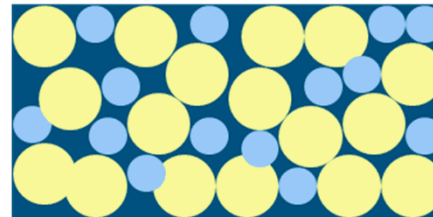
■ Type 2:

- Sinter to full density
- Re-crystallizeable, partial formation of crystalline high Q phases
- Example: Ferro A6



■ Type 3:


- Sinter to high density
- Reactive, forming high Q crystalline phases
- Example: 9k7



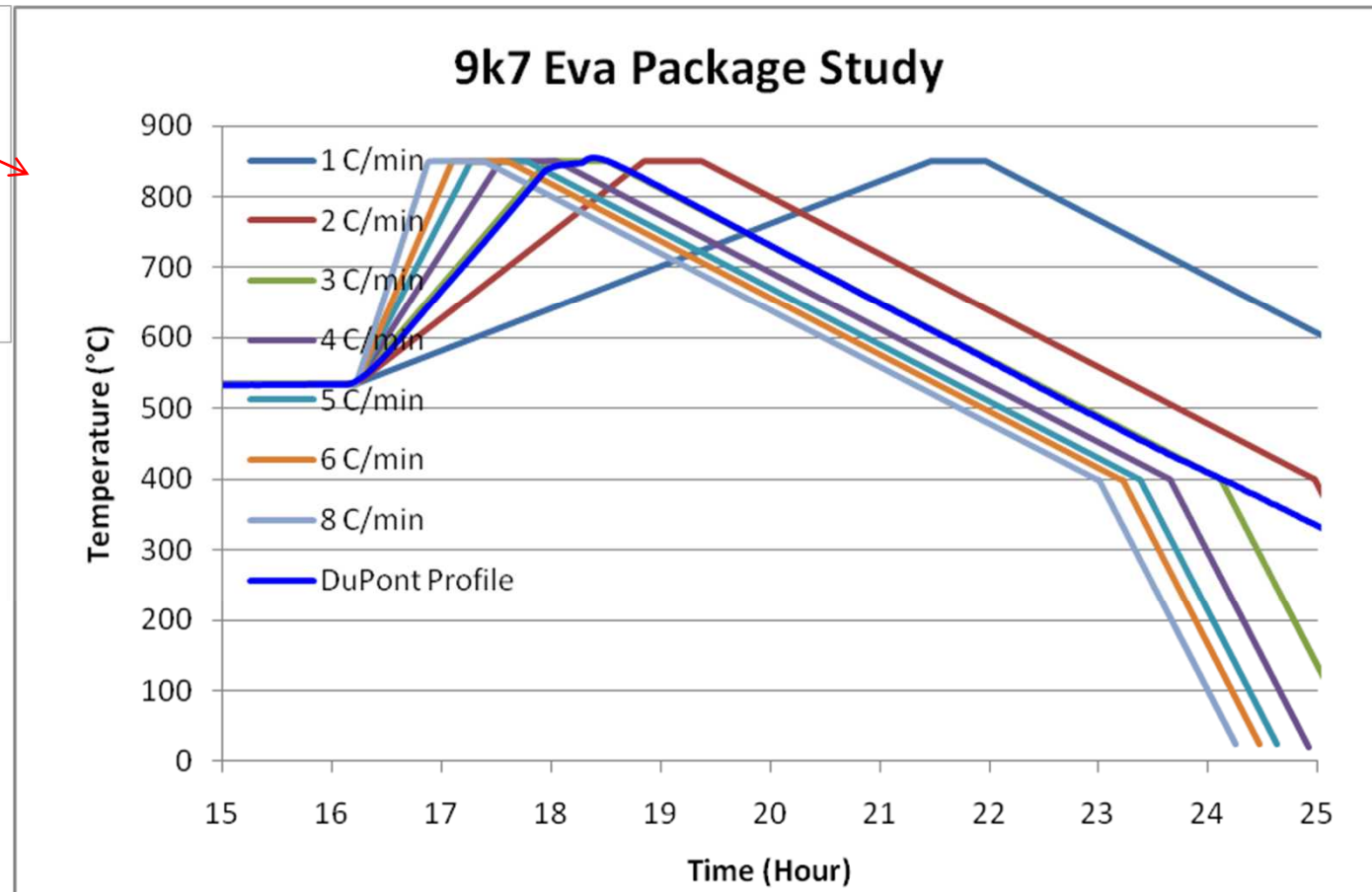
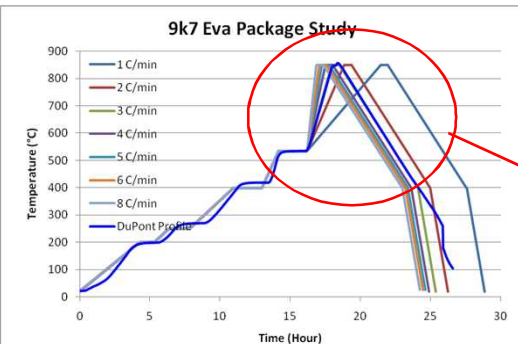
 Organic binder

 Glass

 Ceramic filler (Al_2O_3)

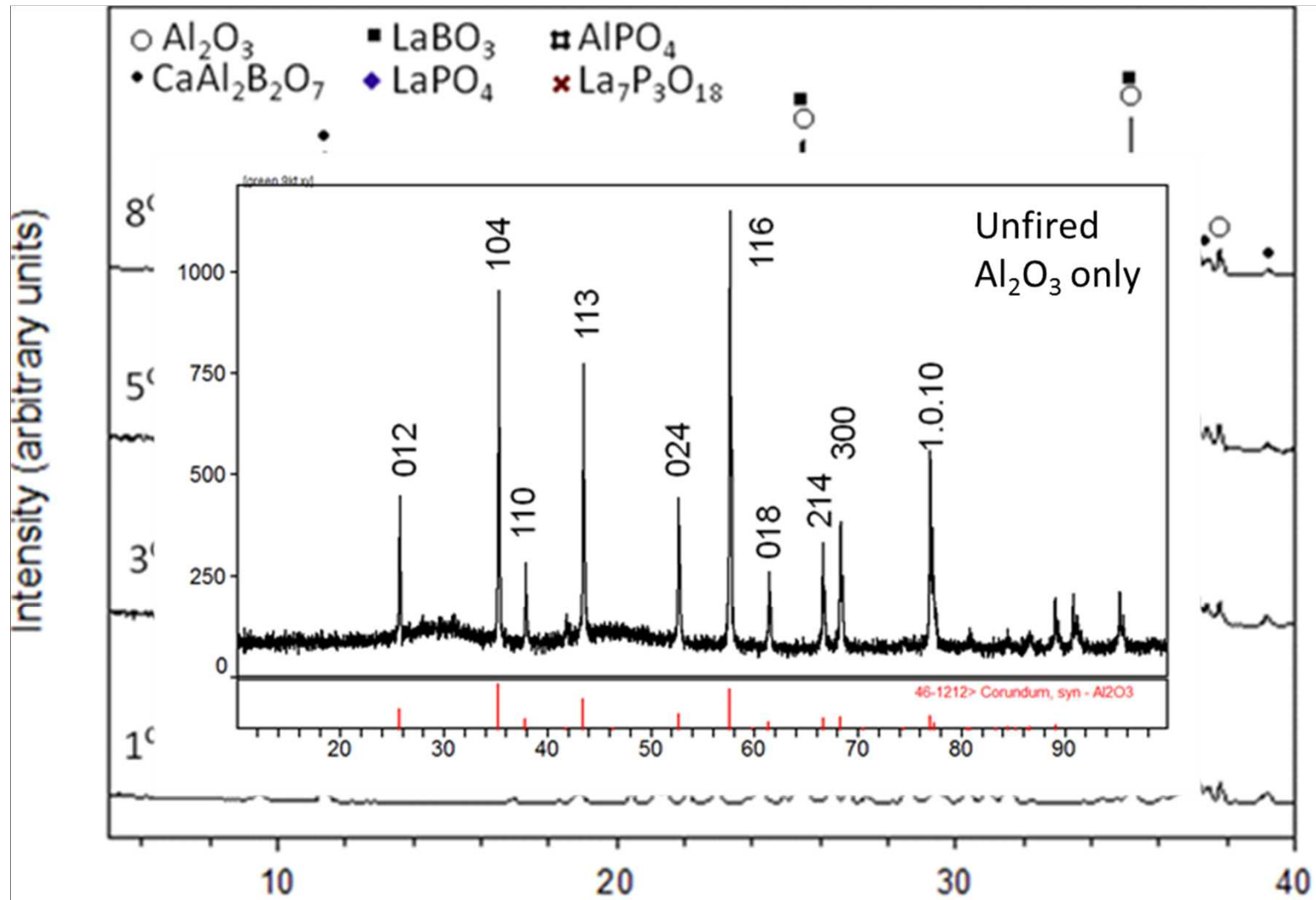
 Crystalline phase

Ramp Rate



- DuPont recommended ramp rate $\sim 2.45^{\circ}$ C/min
- Ramp rate in current study: $1 - 8^{\circ}$ C/min

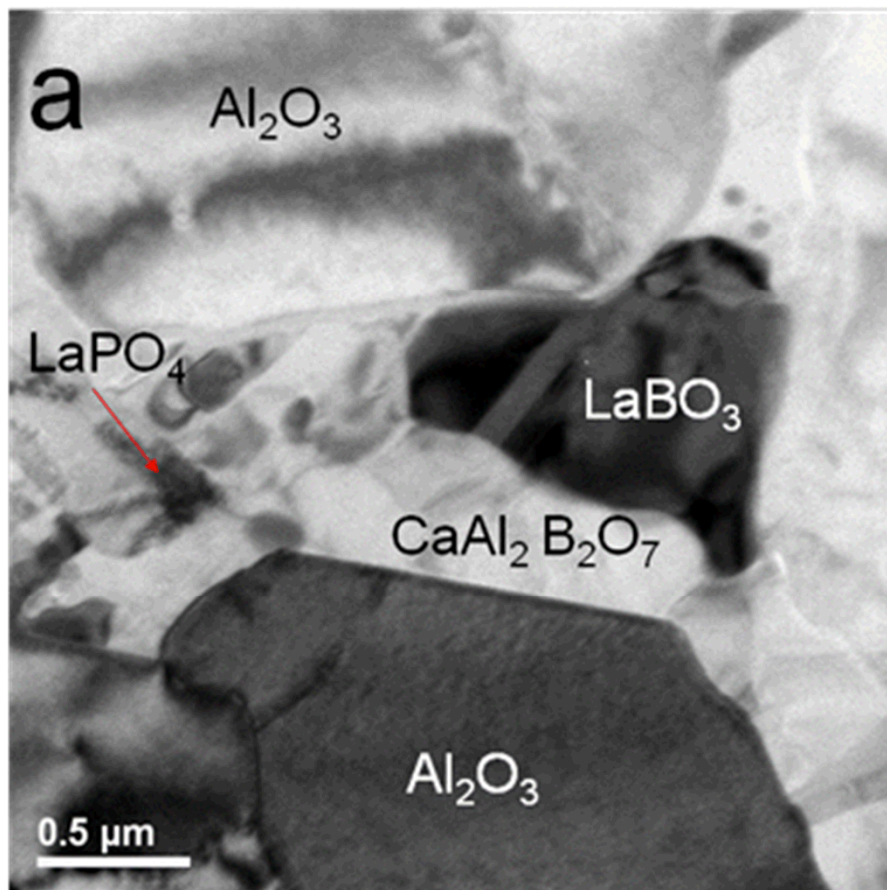
Crystallization in 9k7 LTCC -- XRD



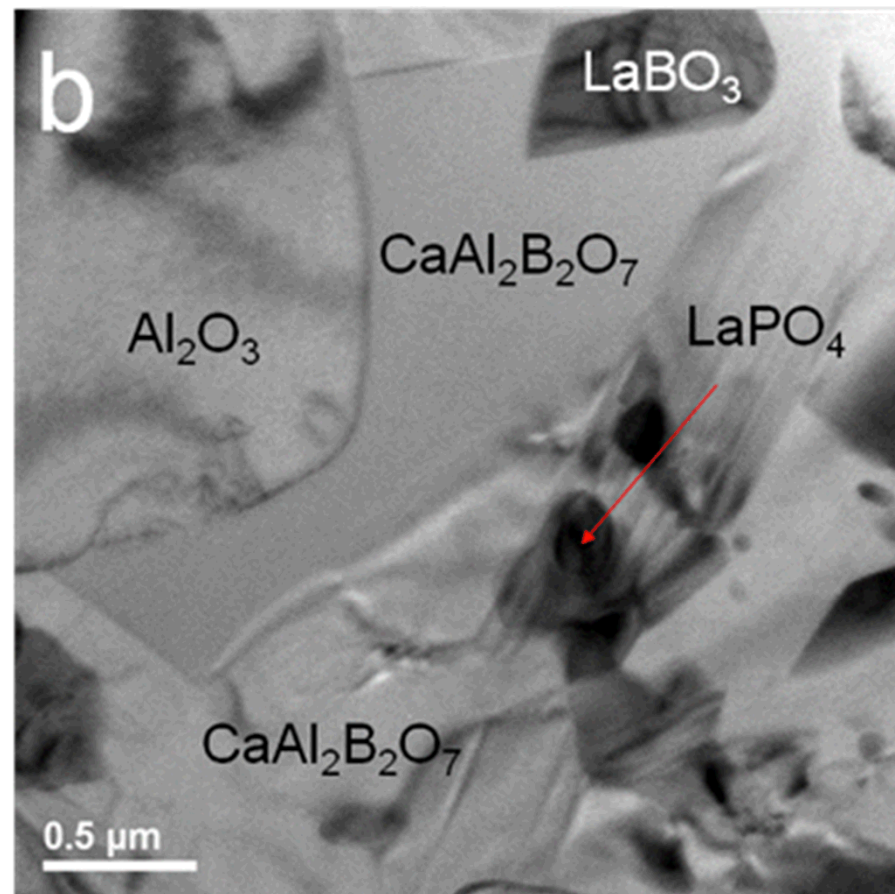
- Both self-derived and reaction-derived crystalline phases

Crystallization in 9k7 LTCC -- TEM

1°C/min



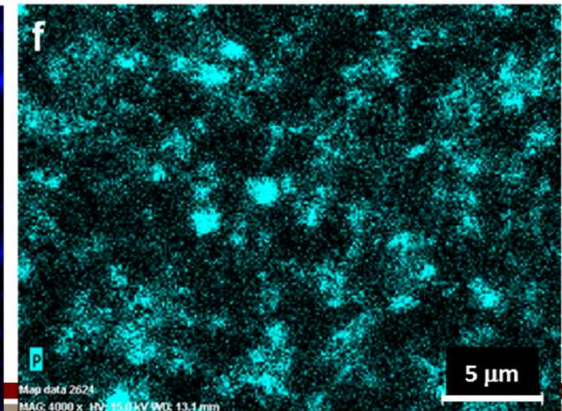
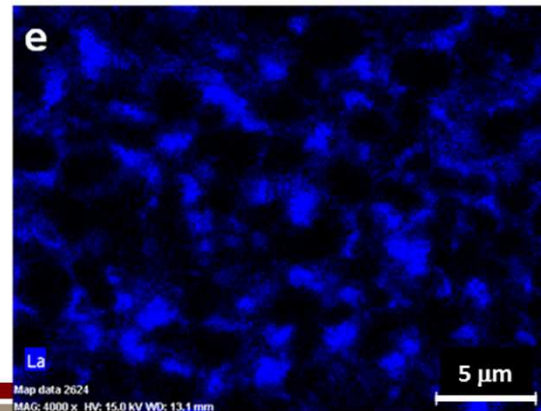
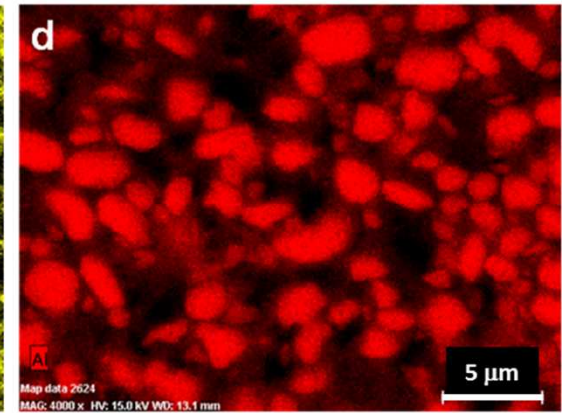
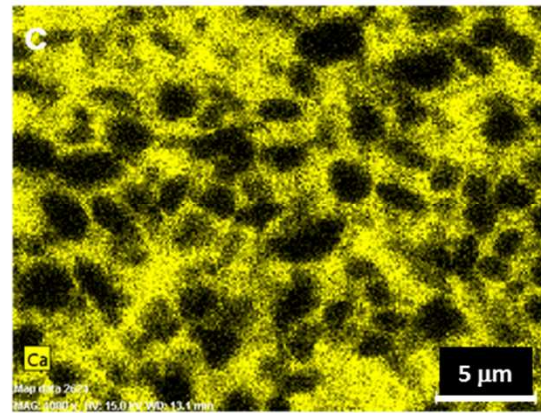
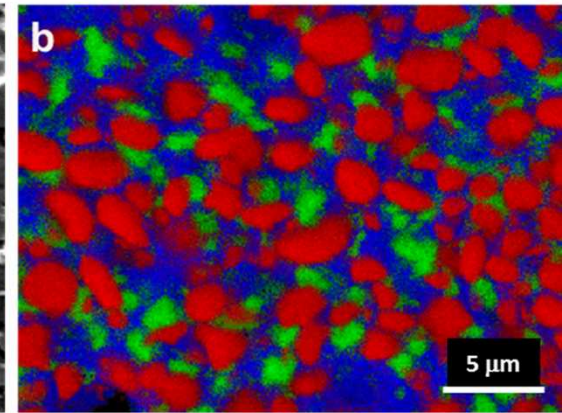
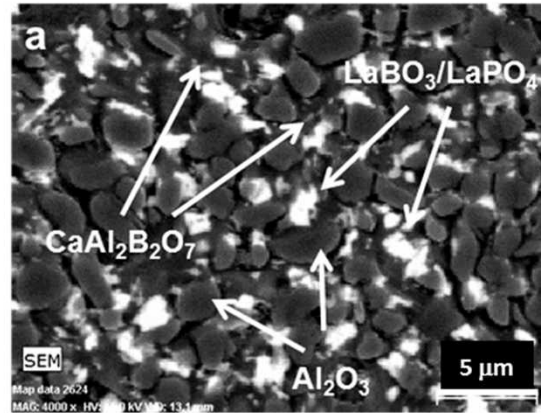
5°C/min



- Al_2O_3 filler
- Continuous reaction-derived $\text{CaAl}_2\text{B}_2\text{O}_7$ phase around Al_2O_3 filler
- Isolated self-derived LaBO_3 and LaPO_4 crystals, away from Al_2O_3

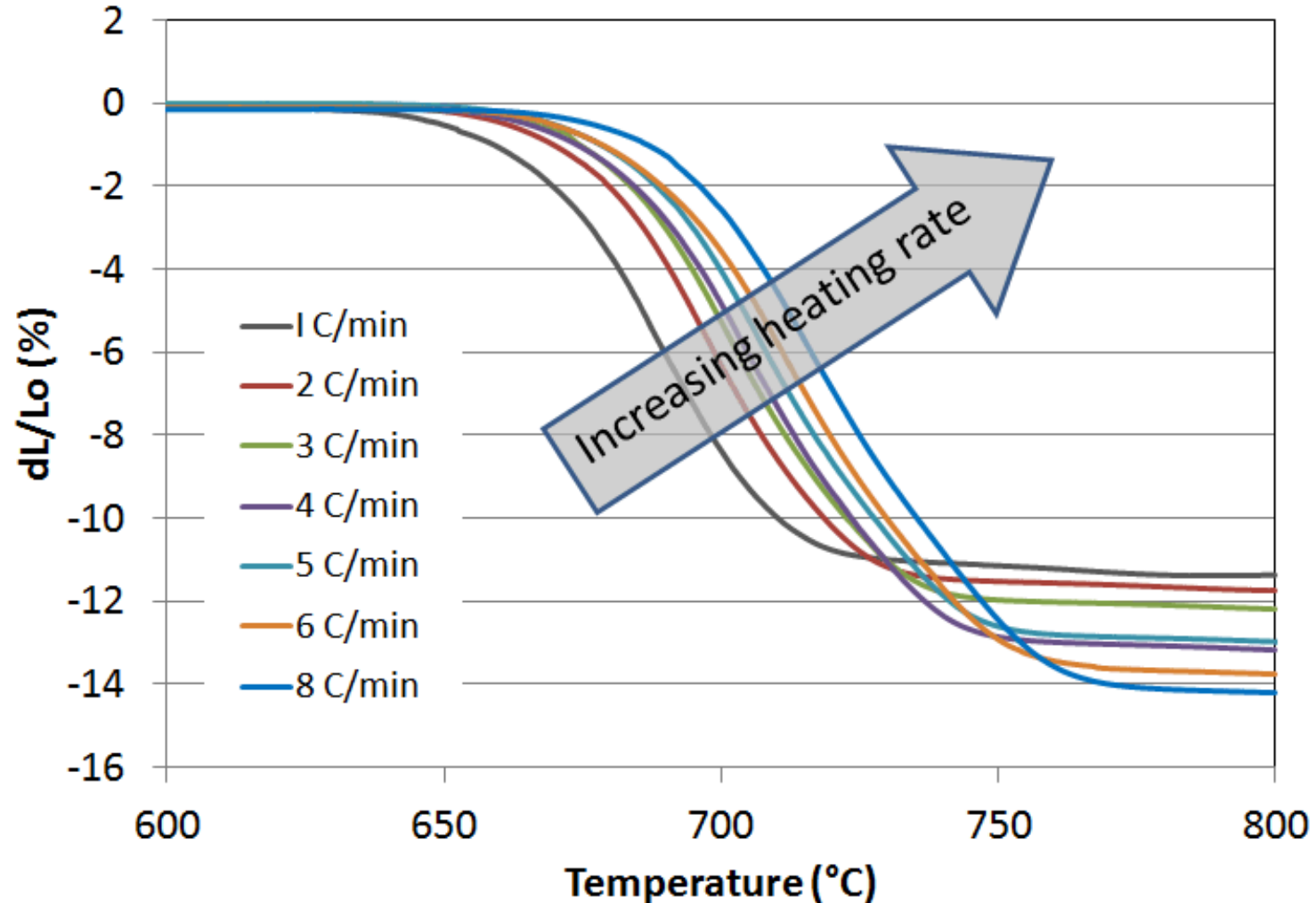
Crystallization in 9k7 LTCC -- SEM

- Phase map from an automated multivariate statistical analysis technique*
 - Red = Al_2O_3
 - Blue = $\text{CaAl}_2\text{B}_2\text{O}_7$
 - Green = $\text{LaBO}_3/\text{LaPO}_4$
- Continuous reaction derived $\text{CaAl}_2\text{B}_2\text{O}_7$ phase
- Isolated self-derived LaBO_3 and LaPO_4 crystals



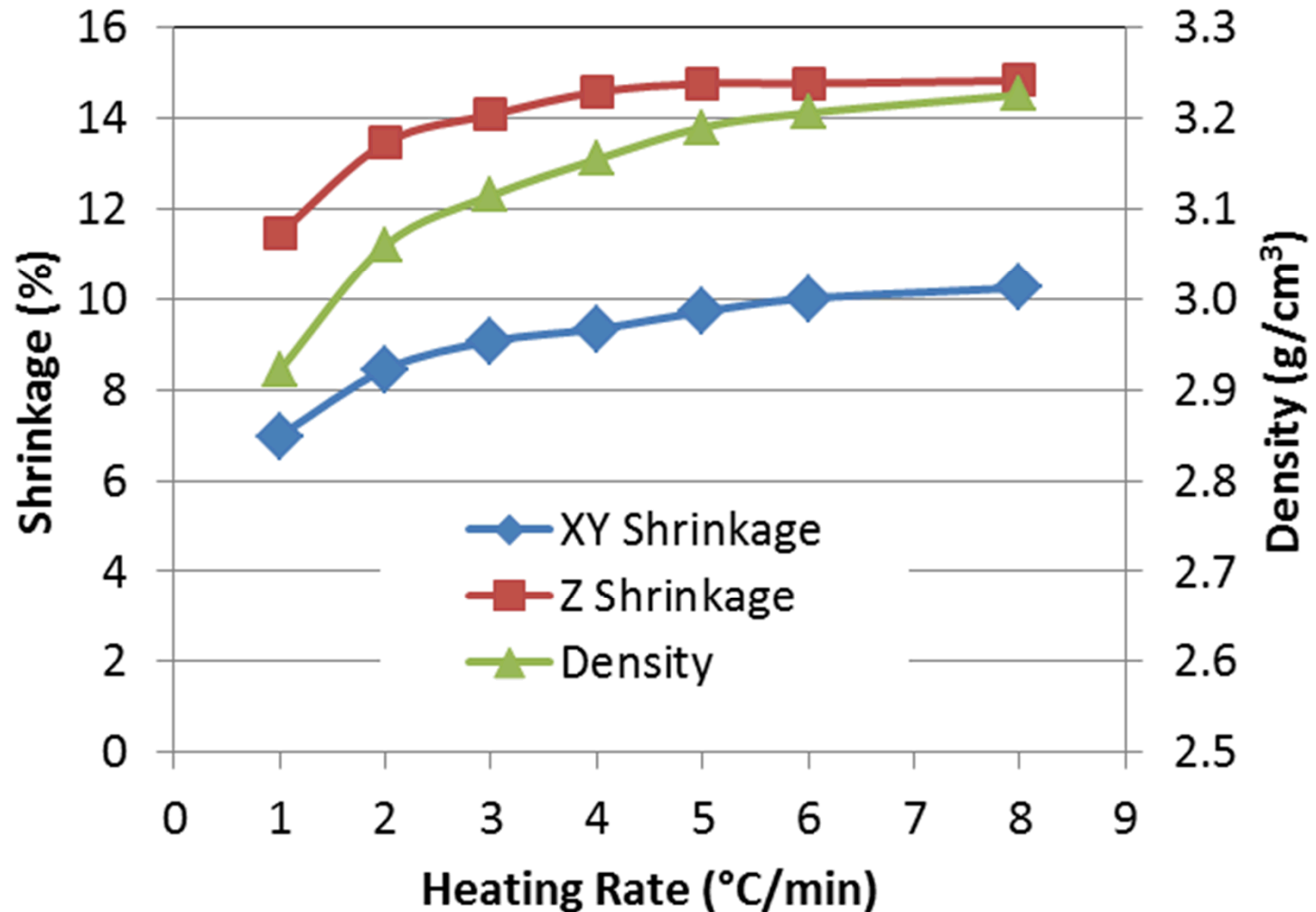
*Kotula, et al, *Microsc. Microanal.* **9**, 1-17 (2003)

9k7 Dilatometry – Z Shrinkage



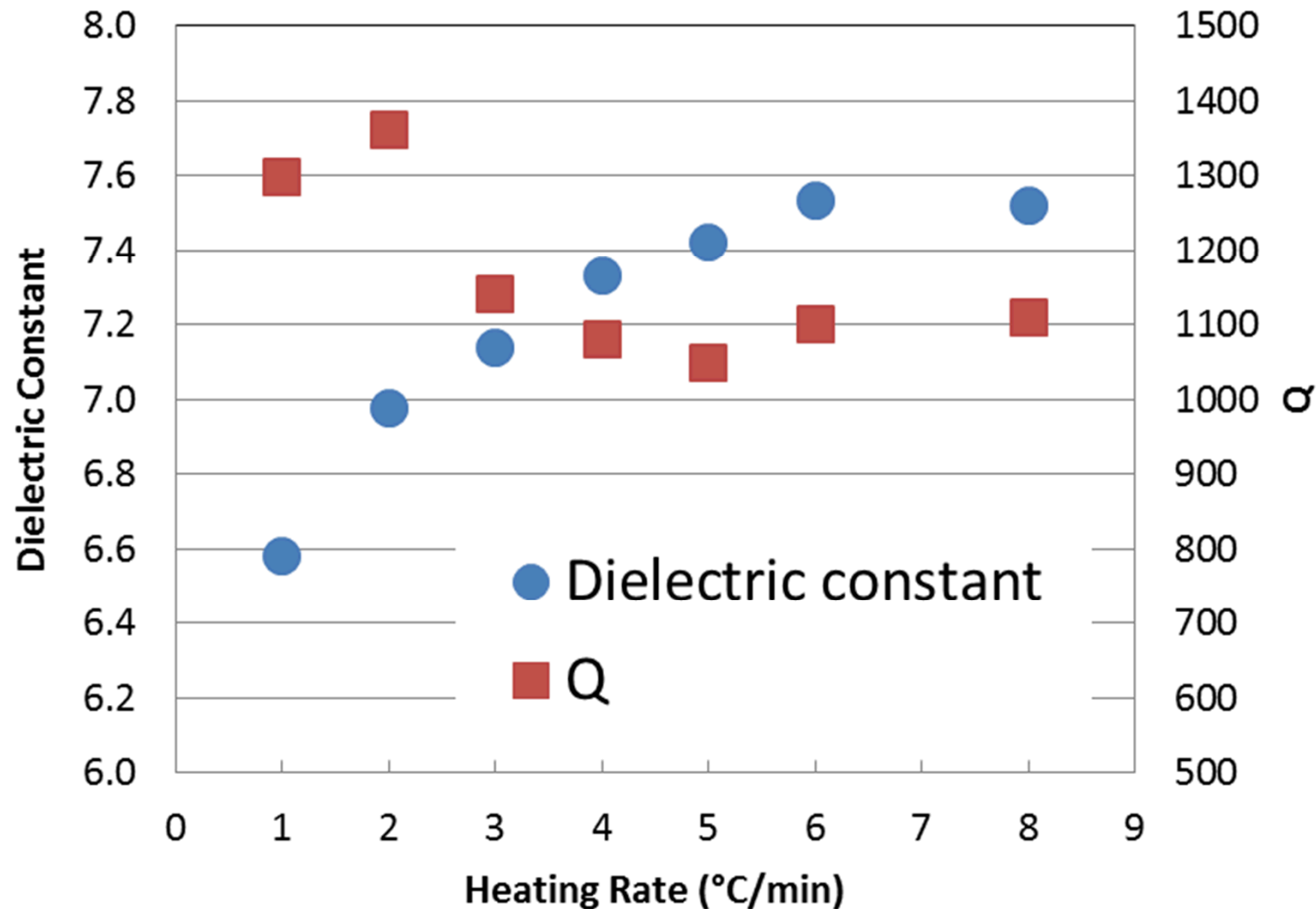
- Ramp-rate dependent shrinkage
- Higher ramp rate \rightarrow more shrinkage

Shrinkage



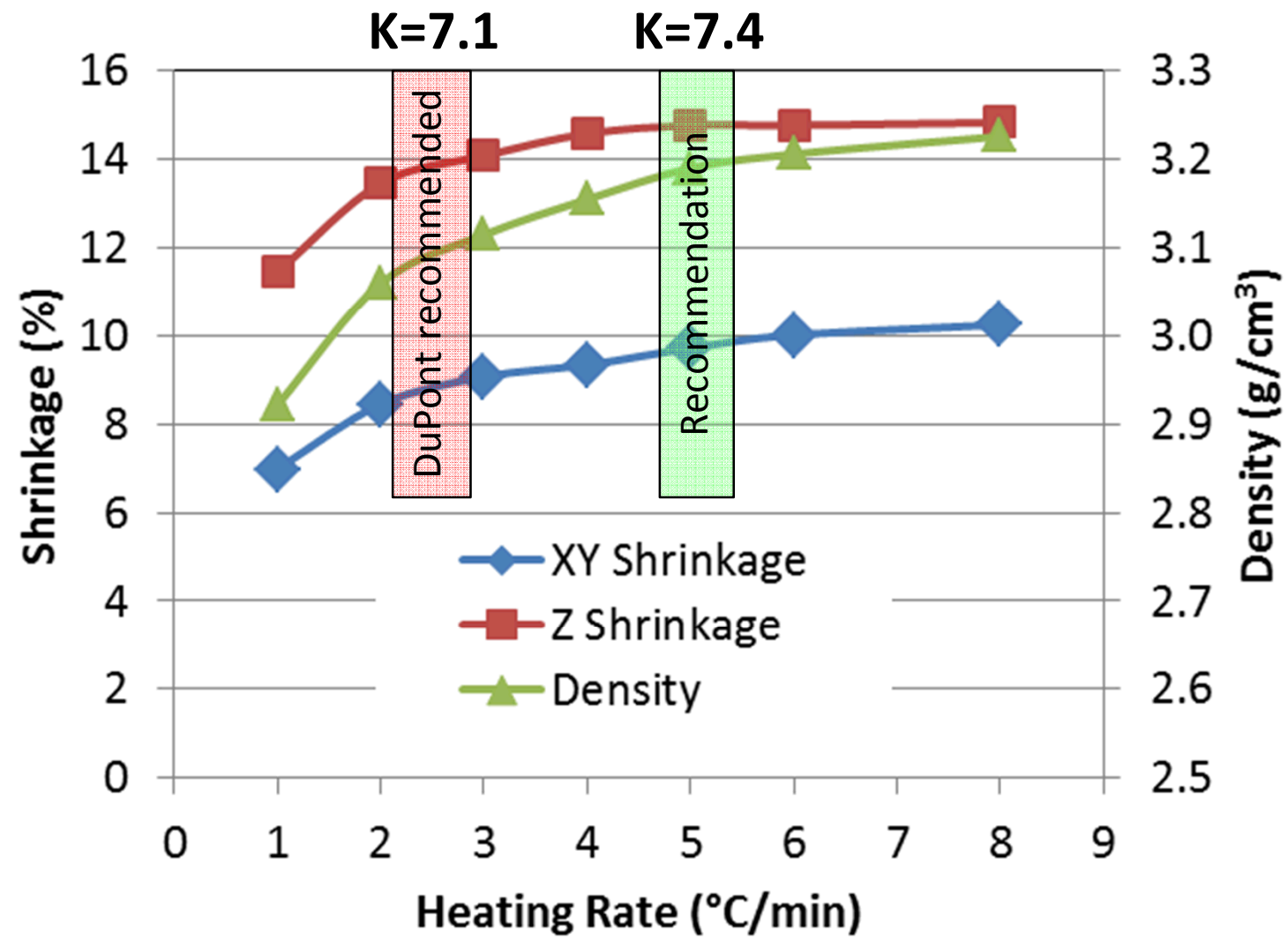
- Both XY&Z shrinkage and density increase as ramp rate increases
- Z reaches plateau while XY and density increase slightly beyond 5 °C/min₀

Dielectric Properties (9.5 GHz)

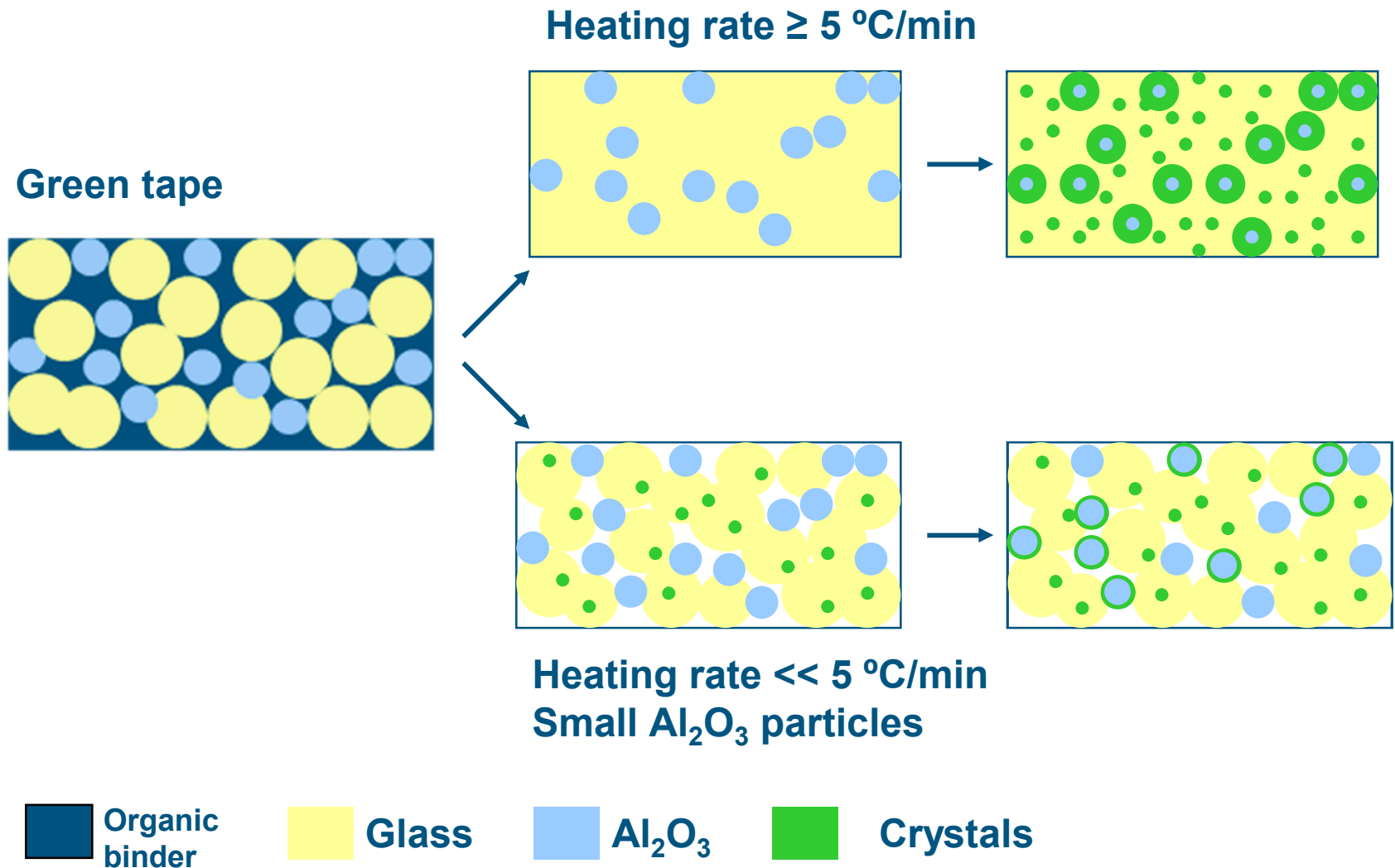


- Split cavity with resonant frequency 10 GHz
- Data validated by Deepu Nair of DuPont
- ϵ increases as density increases
- $Q > 1000$

Process Window of 9k7



Densification vs Crystallization – ramp rate



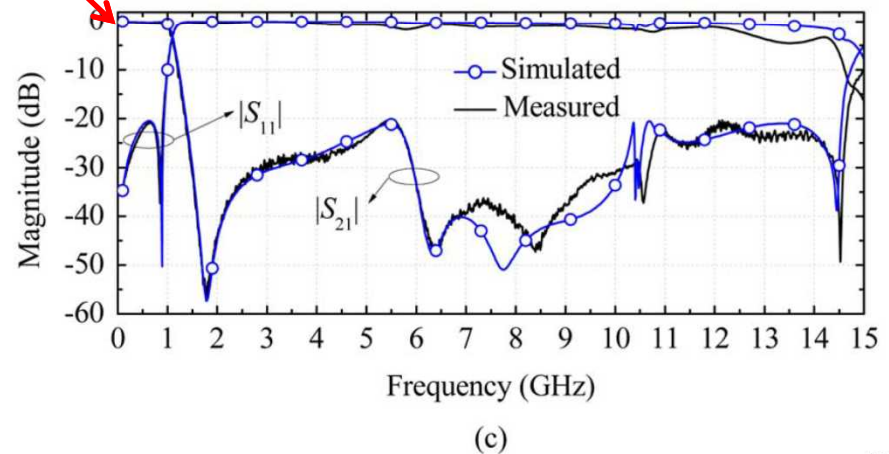
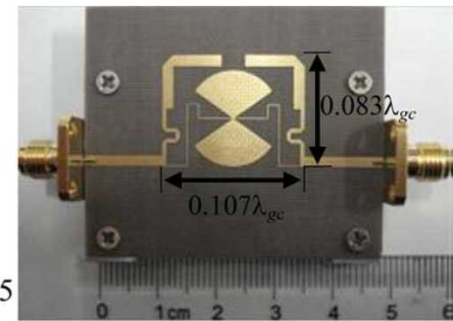
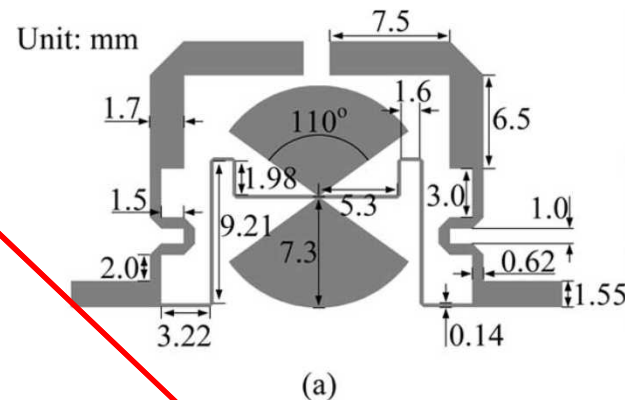
- Enough high ramp rate \rightarrow densification 1st, crystallization 2nd

LPF: single dielectric board

IEEE MICROWAVE AND WIRELESS COMPONENTS LETTERS, VOL. 23, NO. 8, AUGUST 2013

Design of Miniaturized Microstrip LPF and Wideband BPF With Ultra-Wide Stopband

Jin Xu, Yu-Xue Ji, Wen Wu, *Senior Member, IEEE*, and Chen Miao, *Member, IEEE*

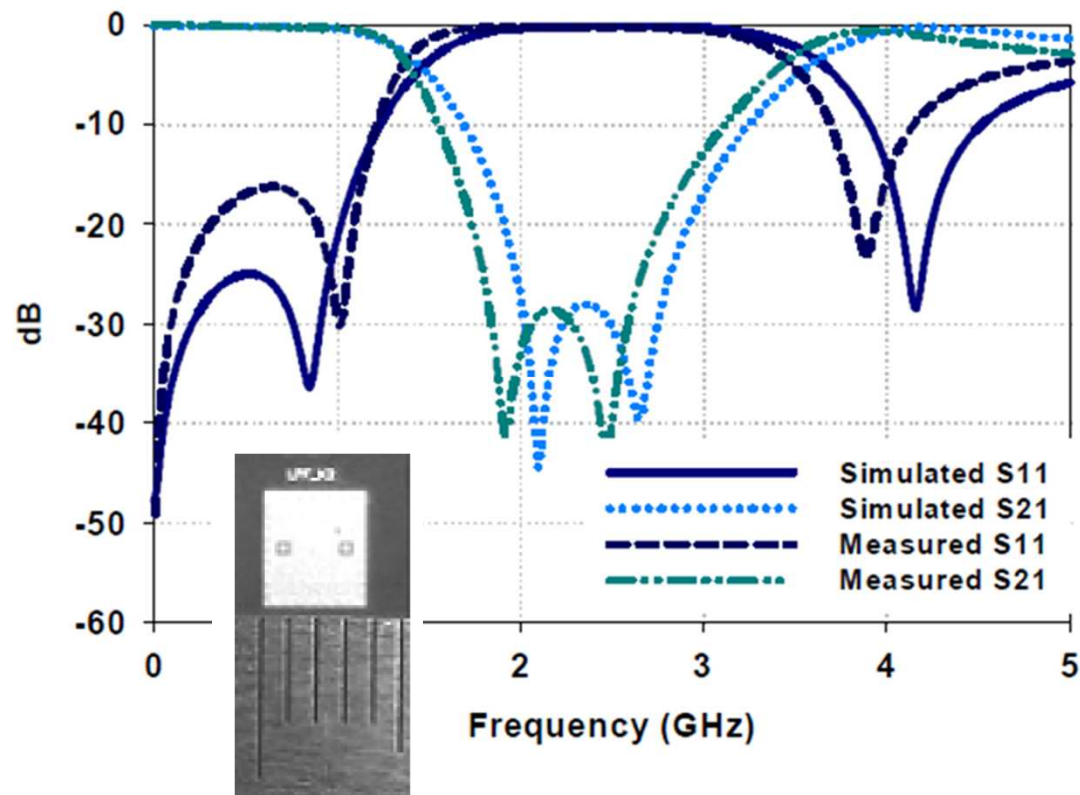


LPF: Multilayer LTCC

- 5 layer DuPont 951 LTCC
 - Combination of 5 mil and 10 mil green tapes
- Size: $3.5 \times 4 \times 0.33$ mm
- Limited stopband

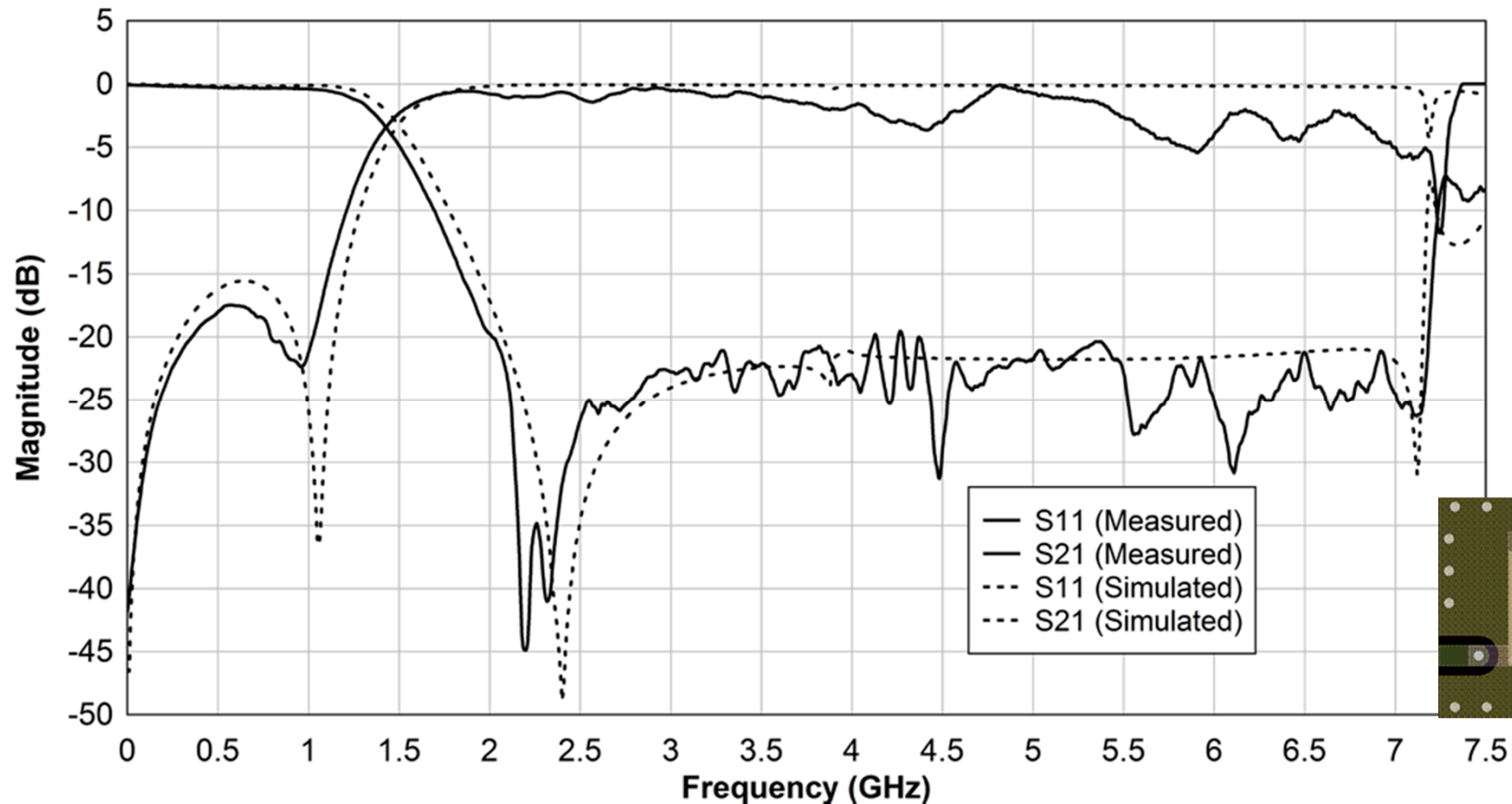
Stacked Lowpass Filter using LTCC Technology

Kyoungkeun Kim, Yuseon Kim, Hyeonsik Na, Jahyeon Lee, Sooman Park, Yeongseog Lim
 Dept. Electronics Engineering, Chonnam National University, Gwang-ju, Korea
 relmk3@empal.com



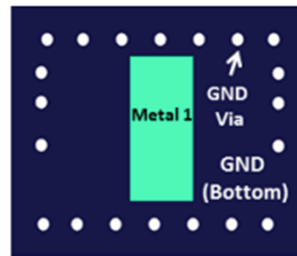
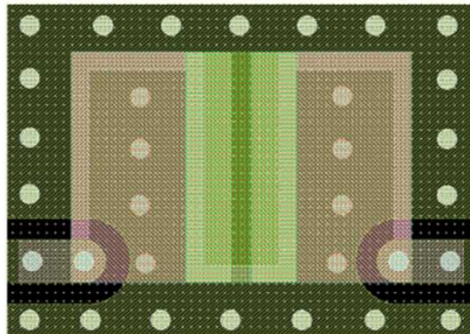
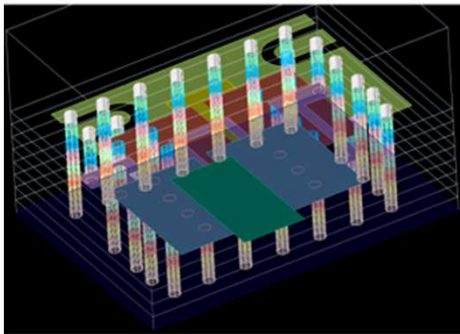
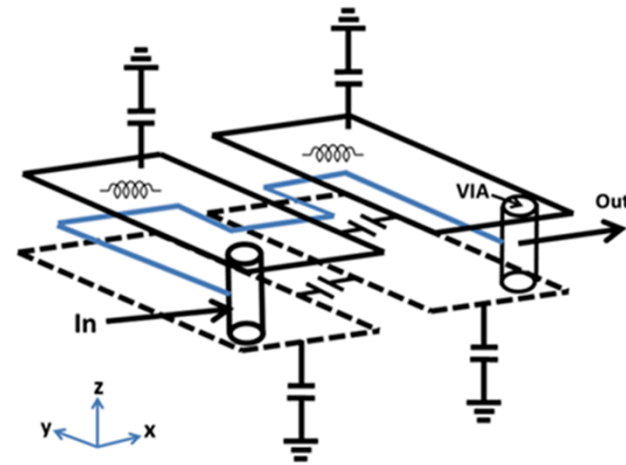
LPF: 4-layer 9k7 LTCC

- Size: 7.5 × 5.5 × 0.85 mm
- Wide stopband to 7.1 GHz (below 19.5 dB)
- Excellent agreement: measured and simulated S-parameters

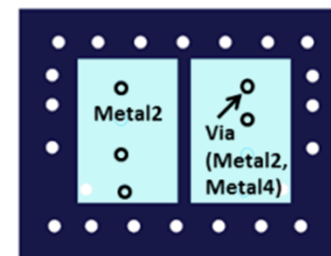


LPF: 8-layer 9k7 LTCC

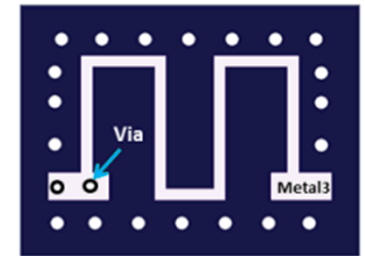
- Size: $5.5 \times 3.9 \times 1.7$ mm
- Standard LTCC processes
- Ramp rate $5^\circ\text{C}/\text{min}$, $\varepsilon = 7.4$



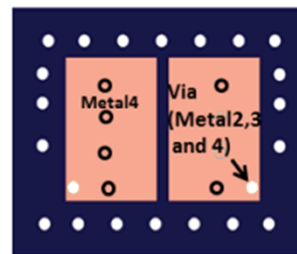
(a)



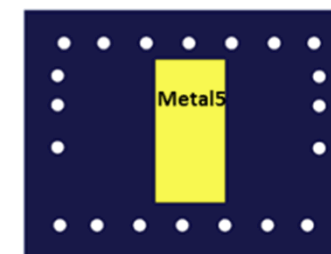
(b)



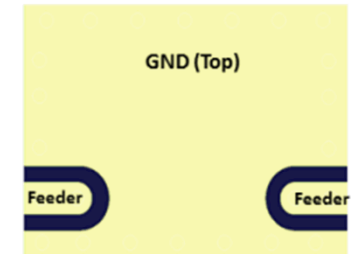
(c)



(d)



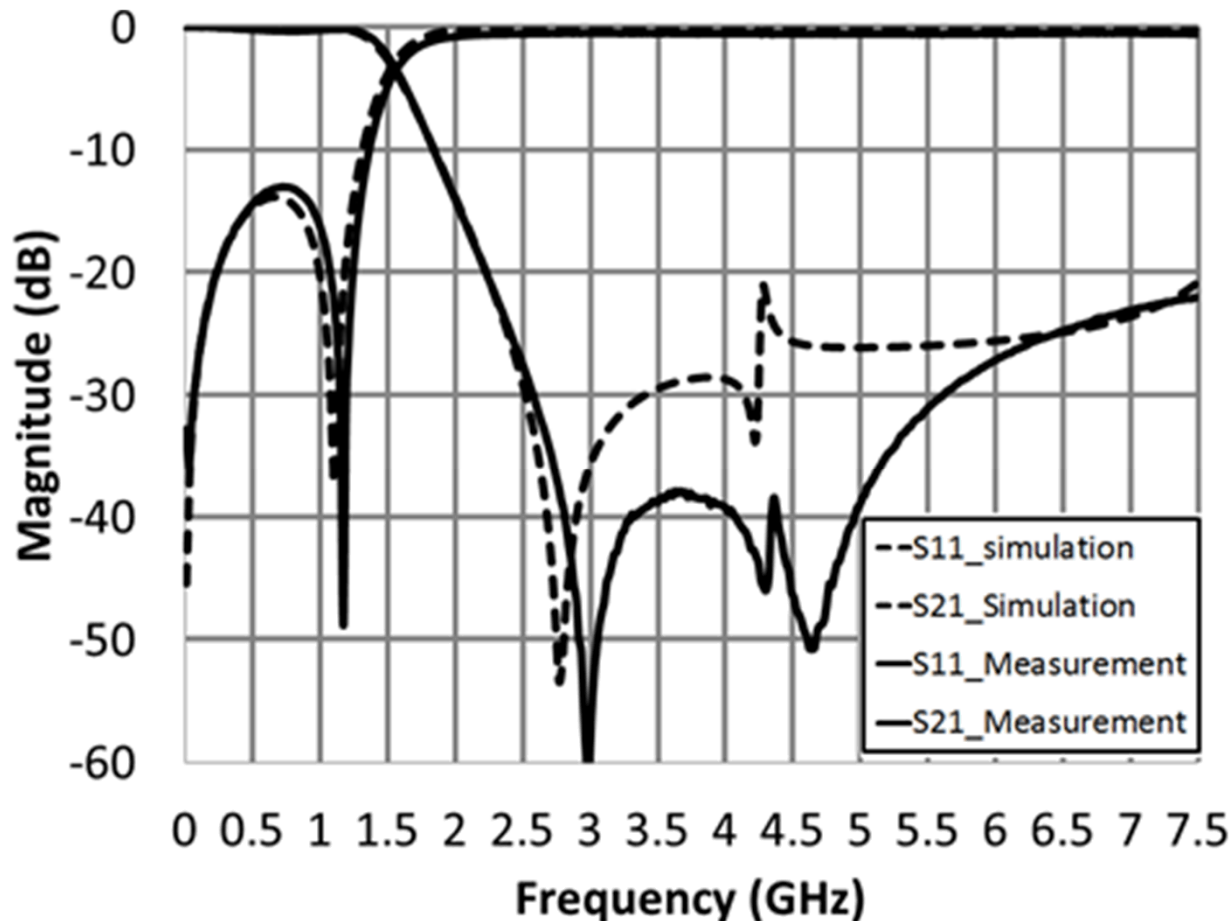
(e)



(f)

LPF: 8-layer 9k7 LTCC

- 3-dB passband from DC to 1.5 GHz. > 22 dB stopband rejection from 2.3 GHz to 7.5 GHz.
- Excellent agreement using $\epsilon = 7.4$



- Competing densification and crystallization in 9k7 LTCC
- Optimization: densification followed by crystallization
 - → ramp rate 5 °C/min
 - $\varepsilon = 7.4$
- LPF with broad stopband demonstrated. Good agreement simulation versus measurement assuming 7.4 dielectric constant